

## PATENT ABSTRACTS OF JAPAN

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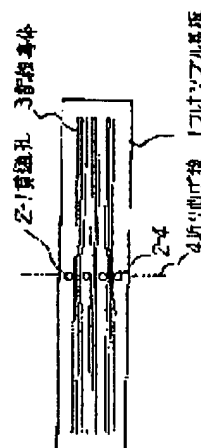
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### (54) FLEXIBLE CIRCUIT BOARD

#### (57)Abstract:

**PURPOSE:** To bend a flexible board after components are placed due to easy bending process, to reduce roundness at a bending position and to reduce entire thickness by providing through holes on a bending line of the board.

**CONSTITUTION:** Through holes 2-1-2-4 each having 2.0mm of diameter are provided at a pitch of 3.5mm along a bending line 4 of a flexible board 1 (insulating resin film having about 200 $\mu$ m of thickness), and wiring conductors 3 of copper foil are disposed between the holes. It is easy to bend along the line, and can be bent after components are placed. The entire thickness after bending is about 5mm in prior art example, but reduced to about 2mm in this embodiment.



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